ADS1118 BoosterPack

TEXAS INSTRUMENTS

Software and Driver Installation

Go to www.ti.com/ADS1118boosterpack. Here, you can download the latest version of ADS1118 BoosterPack firmware

Configuring LaunchPad ____

- Requires LaunchPad. Available at www.ti.com/launchpadwiki
- LaunchPad rev1.4 and below requires cross jumpering the UART lines.
- For LaunchPad rev1.5, switch to hardware UART through J3 jumpers
- Remove P1.6 jumper for I2C operation. Remove P1.0 jumper for Buzzer
- Replace the existing LaunchPad device with the MSP430G2553 device inside the ADS1118 Booster Pack. This device has been pre-loaded with the user experience firmware.
- Insert BoosterPack on top of LaunchPad



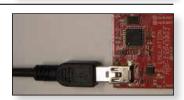
Connecting thermocouple —

Connect a Type K thermocouple probe to J3 on ADS1118 BoosterPack.



Connecting hardware _____

Install the LaunchPad drivers included in the firmware package if needed. Connect LaunchPad using a USB cable to a Windows enabled PC. If prompted, please allow Windows to install the software automatically.



Re-downloading or modifying firmware

The quickest way to re-download firmware image is to use

MSP430Flasher.bat inside bin/firmware folder.

To open the project files and re-compile the firmware, download free and unrestricted compilers & debuggers, including:

- Code Composer StudioTM version 5.3 (CCS)
- IAR Embedded Workbench v5.40.3

Starting the demo application -

Press S2 on LaunchPad for switching temperature display at °C or °F.

TH:0100 00:00:00 Temp: 73.7°F CH0

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